Touch Screen and Membrane Switch Inks and Dielectrics

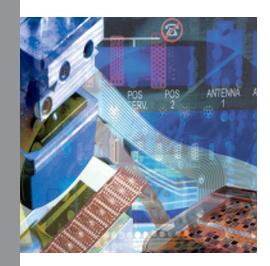
SILVER INKS			
Product #	Sheet Resistivity (ohms/sq/mil)	Comments	
118-09 A/B	0.020	Two component, low temperature cure, solvent resistant ink for polyester and other low temperature substrates. Adheres well to ITO (Indium Tin Oxide) sputtered surfaces.	
125-26 A/B	0.015	Fine line printable (3 to 4 mil), two component, low temperature cure, solvent resistant ink for polyester and other low temperature substrates. Adheres well to ITO (Indium Tin Oxide) sputtered surfaces.	
120-07	0.020	Extremely flexible. Cures at temperatures as low as 50 °C. Screen printable.	
118-41	0.010	Solvent resistant, flexible, silver epoxy ink.	
102-05F	0.019	Bonds to ITO (Indium Tin Oxide) sputtered surfaces. Flexible and screen printable. Temperature, abrasion and chemical resistance.	
125-15	0.010	Exceptional conductivity. Fast curing. (i.e., 3-5 mins. at 110 °C). Screen-printable. Conductivity and cost modification with 112-48 carbon ink.	
101-59	0.015	Exceptional flexibility. Screen-printable.	
125-13	0.015	Fine line printable version of 101-59.	
118-43	0.010	Pad-printable version of 101-59.	
113-37	0.010	Pad-printable conductive ink.	
110-03	0.020	For use in spray, flexographic and rotogravure printing methods. Extremely flexible.	
CARBON INKS			
Product #	Sheet Resistivity (ohms/sq/mil)	Comments	
104-18	75.0	Bonds to ITO (Indium Tin Oxide) sputtered surfaces. Temperature, abrasion and chemical resistance. Can be blended with 102-05F to tailor cost and conductivity of 102-05F. Can be used with 116-20, a flexible UV cured dielectric. Screen printable.	
112-48	20.0	Exceptional conductivity. Screen printable. Fast curing, (i.e., 3-5 mins. at 110 °C). Can be blended with 125-15 to reduce cost and tailor conductivity of 125-15.	
108-46	50.0	Exceptional flexibility. Screen printable. Can be blended with 101-59 for cost and conductivity adjustment of 101-59.	
114-34A/B	150	Two component, low temperature cure, solvent resistant ink for polyester and other low temperature substrates. Adheres well to ITO (Indium Tin Oxide) sputtered surfaces. Carbon version of 118-09A/B.	
119-28	50.0	Pad printable version of 108-46.	
124-50	40.0	Fast drying conductive ink for ITO or polycarbonate substrates.	
DIELECTRIC INK	S		
Product #	Sheet Resistivity (ohms/sq/mil)	Curing Method	Comments
118-12 A/B	450	Thermal	Clear, solvent resistant, flexible, low temperature curing.
118-08 A/B	450	Thermal	Translucent blue, solvent resistant, flexible, low temperature curing.
113-48	525	UV/Thermal	Very flexible.
116-20	365	UV	Clear, UV Curable.
125-17M	365	UV	Matte colorless.
		UV	Matte blue.
125-17MB	365	UV	
125-17MB 125-17MG	365 365	UV	Matte green.
			Matte green.
125-17MG	365	UV	

PLEASE CONTACT US FOR OTHER MARKET SPECIFIC PRODUCT SELECTOR GUIDES



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Creative Materials. Connecting the future with specialty electronic materials.



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Our in-depth experience with conductive filler technology, particle size and shape allows us to fine tune the performance, as well as the application process and cure cycle to best meet our customers' production requirements.

Custom application solutions.

Our core technology base includes: microelectronic grade adhesives; electrically conductive adhesives, coatings and inks; anisotropic conductive adhesives; dielectric adhesives, coatings and inks; thermally conductive adhesives; encapsulating and potting compounds. Application specific products for unique process requirements are the heart of our business.

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We work closely with our customers to reduce their time to market of new products — from initial prototypes to scale-up of production. Our experience spans unique applications in microelectronics, biotechnology, electronics and electrical, medical, automotive, telecommunications and aerospace/ defense markets.

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